



DOCUMENT CHANGE REQUEST

DCR number 182 Changes required for: General
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Originator: S Thacker - ESCC
Organisation: ESA/ESTEC

Title: Generic Specification for Integrated Circuits Monolithic

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Other documents affected:

Page:

editorial changes throughout the spec (see attached mark-up)

Paragraph:

editorial changes throughout the spec (see attached mark-up)

Original wording:

Proposed wording:

(See attached mark-up)

Editorial changes include:

Para 5.1 - add 3rd sub-para from para 6.1 to para 5.1 plus the statement "in the case of lot failure..."

Para 5.2.1 - add reference to para 8.2 and criteria for lot failure

Para 9.1 - incorporate the content of bullet (h) into (g)

Para 12.2 Chart F2 - amend para references in Special In-process Controls to be from para 5 instead of para 8

Make terminology used consistent e.g.

"Component Type Qualification Testing" instead of "Qualification Tests"

"Periodic Testing" instead of "Periodic Tests"

"Room Temperature Electrical Measurements" instead of "Electrical Measurements at Room Temperature"

"External Visual Inspection failure" instead of "Visual Inspection failure"

"qualification, qualification maintenance and Lot Validation Testing" instead of "Qualification and Periodic Tests"

"Screening Tests" instead of "Screening"

Capitalisation of reference terminology

Justification:



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Editorial amendments are included for the purposes of consistency within the document and with other ESCC generic specifications; plus for the purposes of clarification.

Attachments:

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Modifications:

N/A

Approval signature:

Date signed:

2005-06-03

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NEXT ISSUE 4



Pages 1 to 27

INTEGRATED CIRCUITS, MONOLITHIC, HERMETICALLY SEALED

ESCC Generic Specification No. 9000

⁴ Issue 3 Draft A	June 2005 September 2004
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DCR No.	CHANGE DESCRIPTION
138	Specification upissued to incorporate editorial and technical changes per DCR.

148, TBD

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1. INTRODUCTION

1.1 SCOPE

This specification defines the general requirements for the qualification, qualification maintenance, procurement, and delivery of hermetically sealed monolithic integrated circuit components for space applications. This specification contains the appropriate inspection and test schedules and also specifies the data documentation requirements.

1.2 APPLICABILITY

This specification is primarily applicable to the granting of qualification approval to a component in accordance with ESCC Basic Specification No. 20100 or 24300 and the procurement of such components from qualified or capability approved Manufacturers. It may also be applied for procurement of unqualified components.

2. APPLICABLE DOCUMENTS

The following documents form part of, and shall be read in conjunction with, this specification. The relevant issues shall be those in effect on the date of starting qualification or placing the Purchase Order.

2.1 ESCC SPECIFICATIONS

- No. 20100, Requirements for the Qualification of Standard Electronic Components for Space Application.
- No. 20400, Internal Visual Inspection.
- No. 20500, External Visual Inspection.
- No. 20600, Preservation, Packaging and Dispatch of ESCC Electronic Components.
- No. 21300, Terms, Definitions, Abbreviations, Symbols and Units.
- No. 21400, Scanning Electron Microscope Inspection of Semiconductor Dice.
- No. 21700, General Requirements for the Marking of ESCC Components.
- No. 22800, ESCC Non-conformance Control System.
- No. 22900, Total Dose Steady-State Irradiation Test Method.
- No. 23500, Lead Materials and Finishes for Components for Space Application.
- No. 23800, Electrostatic Discharge Sensitivity Test Method.
- No. 24300, Requirements for the Capability Approval of Electronic Component Technologies for Space Application.
- No. 24600, Minimum Quality System Requirements.
- No. 24800, Resistance to Solvents of Marking, Materials and Finishes.

For qualification and qualification maintenance or procurement of qualified components, with the exception of ESCC Basic Specifications Nos. 20100, 21700, 22800, 24300 and 24600, where Manufacturers' specifications are equivalent to, or more stringent than, the ESCC Basic Specifications listed above, they may be used in place of the latter, subject to the approval of the ESCC Executive.

Such replacements shall be clearly identified in the applicable Process Identification Document (PID).

For procurement of unqualified components, where Manufacturers' specifications are equivalent to or more stringent than the applicable ESCC Basic Specifications listed above, they may be used in place of the latter subject to the approval of the Orderer.

Such replacements may be listed in an appendix to the appropriate Detail Specification at the request of the Manufacturer or Orderer, subject to the approval of the ESCC Executive.

Unless otherwise stated herein, references within the text of this specification to "the Detail Specification" shall mean the relevant ESCC Detail Specification.

2.2 OTHER (REFERENCE) DOCUMENTS

- ECSS-Q-70-02, A Thermal Vacuum Test for the Screening of Space Materials.
- MIL-STD-883, Test Methods and Procedures for Micro-electronics.

2.3 ORDER OF PRECEDENCE

For the purpose of interpretation and in case of conflict with regard to documentation, the following order of precedence shall apply:

- (a) ESCC Detail Specification.
- (b) ESCC Generic Specification.
- (c) ESCC Basic Specification.
- (d) Other documents, if referenced herein.

3. TERMS, DEFINITIONS, ABBREVIATIONS, SYMBOLS AND UNITS

The terms, definitions, abbreviations, symbols and units specified in ESCC Basic Specification No. 21300 shall apply.

4. REQUIREMENTS

4.1 GENERAL

The test requirements for the component type qualification of a component shall comprise Special In-Process Controls, Wafer Lot Acceptance with radiation tests (if specified), Screening Tests and Qualification Tests.
Component Type

The requirements for approval of a capability domain and the qualification of a component (type approval testing) within an approved domain are given in ESCC Basic Specification No. 24300.

The test requirements for procurement of components shall comprise Special In-Process Controls, Wafer Lot Acceptance with radiation tests if required in the Purchase Order, Screening Tests, together with Periodic Tests for qualified components and Lot Validation Testing for qualified (if required in the Purchase Order) and unqualified components (see Chart F1).
ing

4.1.1 Specifications

For qualification, qualification maintenance, procurement and delivery of components in conformity with this specification, the applicable specifications listed in Section 2 of this document shall apply in total unless otherwise specified herein or in the Detail Specification.

4.1.2 Conditions and Methods of Test

The conditions and methods of test shall be in accordance with this specification, the ESCC Basic Specifications referenced herein and the Detail Specification.



4.1.3 Manufacturer's Responsibility for Performance of Tests and Inspections

The Manufacturer shall be responsible for the performance of tests and inspections required by the applicable specifications. These tests and inspections shall be performed at the plant of the Manufacturer of the components unless it is agreed by the ESCC Executive (for qualification, qualification maintenance, or procurement of qualified components) or the Orderer (for procurement of unqualified components), to use an approved external facility.

4.1.4 Inspection Rights

The ESCC Executive (for qualification, qualification maintenance, or procurement of qualified components) or the Orderer (for procurement of unqualified components) reserves the right to monitor any of the tests and inspections scheduled in the applicable specifications.

4.1.5 Pre-encapsulation Inspection Witnessing

If required in the Purchase Order, the Orderer may witness or perform the pre-encapsulation inspection and the Manufacturer must notify the Orderer at least 2 working weeks before the commencement of the inspection.

4.2 QUALIFICATION AND QUALIFICATION MAINTENANCE REQUIREMENTS ON A MANUFACTURER

To obtain and maintain the component type qualification of a component, or family of components, a Manufacturer shall satisfy the requirements of ESCC Basic Specification No. 20100.

To obtain and maintain the qualification of a component in a capability approved domain, a Manufacturer shall satisfy the requirements of ESCC Basic Specification No. 24300.

4.3 DELIVERABLE COMPONENTS

Components delivered to this specification shall be processed and inspected in accordance with the relevant Process Identification Document (PID). Each delivered component shall be traceable to its production lot. Components delivered to this specification shall have satisfactorily completed all the required tests.

ESCC qualified components delivered to this specification shall be produced from lots that are capable of passing all applicable tests, and sequences of tests, that are defined in Chart F4. The Manufacturer shall not knowingly supply components that cannot meet this requirement. In the event that, subsequent to delivery and prior to operational use, a component is found to be in a condition such that it could not have passed these tests at the time of manufacture, this shall be grounds for rejection of the delivered lot.

4.3.1 Lot Failure

(Chart F2) (Chart F2) (Chart F3)

Lot failure may occur during Special In-Process Controls, Wafer Lot Acceptance, Screening Tests, or Qualification and Periodic Tests

(Chart F4)

Should such failure occur during qualification, qualification maintenance or procurement of qualified components the Manufacturer shall initiate the non-conformance procedure in accordance with ESCC Basic Specification No. 22800. The Manufacturer shall notify the Orderer and the ESCC Executive by any appropriate written means, within 5 working days, giving details of the number and mode of failure and the suspected cause. No further testing shall be performed on the failed components.

Should such failure occur during procurement of unqualified components the Manufacturer shall notify the Orderer by any appropriate written means within 5 working days, giving details of the number and mode of failure and the suspected cause. No further testing shall be performed on the failed components.



The Orderer shall inform the Manufacturer within 5 working days of receipt of notification what action shall be taken.

4.4 MARKING

All components procured and delivered to this specification shall be marked in accordance with ESCC Basic Specification No. 21700.

4.5 MATERIALS AND FINISHES

Specific requirements for materials and finishes are specified in the Detail Specification. Where a definite material or finish is not specified a material or finish shall be used so as to ensure that the component meets the performance requirements of this specification and the Detail Specification. Acceptance or approval of any constituent material or finish does not guarantee acceptance of the finished product.

Unless otherwise specified in the Detail Specification the component shall be hermetically sealed and shall have a metal body with hard glass seal or a ceramic body. The component case lid shall be welded, brazed, preform soldered or glass frit sealed.

All non-metallic materials and finishes, that are not within a hermetically sealed enclosure, of the components specified in the Detail Specification shall meet the outgassing requirements as outlined in ECSS-Q-70-02.

4.6 RADIATION TESTING

For qualification or qualification maintenance radiation testing shall be performed when specified in the Detail Specification to the total dose level given.

For procurement as required in the Purchase Order radiation testing shall be performed to the total dose level given in the Detail Specification or to an alternate level if so required in the Purchase Order.

The qualification status of the procured components shall not be impacted by any change to the total dose level applied.

For procurement any lot of components that fails the required total dose radiation test level may be accepted to a lower level of radiation subject to satisfactory test results at the lower level. In this case the total dose radiation level letter for the lot shall be modified accordingly.

5. PRODUCTION CONTROL

5.1 GENERAL

The minimum requirements for production control are defined in the Process Identification Document (PID).

Unless otherwise specified in the Detail Specification all lots of components used for qualification and qualification maintenance, Lot Validation Testing and for delivery shall be subject to tests and inspections in accordance with Chart F2. The applicable test requirements are detailed in the paragraphs referenced

ditto from 6.2

→ Any components. ←

In the case of lot failure, the Manufacturer shall act in accordance with Para. 6.3.1

in Chart F2.

5.1.1 Rebonding

The rebonding of wires during assembly is not permitted.

5.2 SPECIAL IN-PROCESS CONTROLS

5.2.1 Pre-encapsulation Inspection

Pre-encapsulation inspection shall consist of Internal Visual Inspection in accordance with Para. 8.1 plus ~~Bond Strength and Die Shear~~ tests in accordance with Para. 8.2.

These tests are
Bond Strength and Die Shear tests are considered as destructive and therefore components so tested shall not form part of the delivery lot.

5.2.2 Dimension Check

In accordance with Para. 8.10 on 3 samples only.

If a failure occurs, the complete lot shall be checked.

shall be performed on test samples in accordance with Para 8.2. A single failure shall be cause for lot failure.

5.2.3 Weight

The maximum weight of the component ~~is~~ specified in the Detail Specification ~~is~~ shall be guaranteed but not tested.

5.2.4 Documentation

Documentation of Special In-Process Controls shall be in accordance with Para. 9.5.

5.3 WAFER LOT ACCEPTANCE

5.3.1 Process Monitoring Review

Process monitoring review shall be done in compliance with the Manufacturer's SPC rules described in the PID.

A wafer shall be rejected if one or more process control data parameters exceed the allowed distribution as specified in the PID.

5.3.2 Scanning Electron Microscope (SEM) Inspection

Components supplied to this specification shall be produced from wafer lots that have been subjected to, and successfully met, the scanning electron microscope inspection requirements in accordance with Para. 8.3.

5.3.3 Total Dose Radiation Testing

For qualification or qualification maintenance:

- If specified in the Detail Specification, components shall be produced from a wafer lot which has been subjected to and successfully completed Total Dose Radiation Testing in accordance with Para. 8.4 to the total dose level given.

During procurement:

- If specified in the Detail Specification and required in the Purchase Order, components shall be produced from a wafer lot which has been subjected to and successfully completed Total Dose Radiation Testing in accordance with Para. 8.4 to the required total dose level.

5.3.4 Documentation

Documentation of Wafer Lot Acceptance shall be in accordance with Para. 9.6.

6. SCREENING TESTS

6.1 GENERAL

Unless otherwise specified in the Detail Specification, all components used for qualification and qualification maintenance, Lot Validation Testing, and for delivery, shall be subjected to tests and inspections in accordance with Chart F3. All components shall be serialised prior to the tests and inspections.

Unless otherwise specified in the Detail Specification, the tests shall be performed in the order shown.

S-1
ditto
* ↑ [Any components which do not meet these requirements shall be removed from the lot and at no future time be resubmitted to the requirements of this specification.

The applicable test methods and conditions are specified in the paragraphs referenced in Chart F3.

6.2 FAILURE CRITERIA

6.2.1 Environmental and Mechanical Test Failure

The following shall be counted as component failures:- components which fail during tests for which the pass/fail criteria are inherent in the test method, i.e. PIND, Solderability, Seal.

6.2.2 Parameter Drift Failure

The acceptable change limits are shown in Parameter Drift Values in the Detail Specification. A component shall be counted as a parameter drift failure if the changes during High Temperature Reverse Bias Burn-in or during Power Burn-in are larger than the drift values (Δ) specified.

6.2.3 Parameter Limit Failure

A component shall be counted as a limit failure if one or more parameters exceed the limits shown in Electrical Measurements ^{or} Room High and Low Temperatures in the Detail Specification.

Room Temperature ↑ Any component which exhibits a limit failure prior to the submission to HTRB Burn-in shall be rejected and not counted when determining lot rejection.

6.2.4 Other Failures

A component shall be counted as a failure in any of the following cases:

- External Visual Inspection failure.
- Mechanical failure.
- Handling failure.



- Lost component.

6.3 **FAILED COMPONENTS**

A component shall be considered as a failed component if it exhibits one or more of the failure modes described in Para. 6.2.

6.4 **LOT FAILURE**

In the case of lot failure, the Manufacturer shall act in accordance with Para. 4.3.1.

6.4.1 **Lot Failure during 100% Testing**

If the number of components failed on the basis of the failure criteria specified in Paras. 6.2.2 and 6.2.3 exceeds 5% (rounded upwards to the nearest whole number) of the components submitted to initial measurements of Parameter Drift Values of Chart F3, the lot shall be considered as failed.

If a lot is composed of groups of components of one family defined in one ESCC Detail Specification, but separately identifiable for any reason, then the lot failure criteria shall apply separately to each identifiable group.

6.4.2 **Lot Failure during Sample Testing**

A lot shall be considered as failed if the number of allowable failures during sample testing as specified in the Detail Specification, is exceeded.

If a lot failure occurs, a 100% testing may be performed but the cumulative percent defective shall not exceed that given in Para. 6.4.1.

No failures are allowed for the Solderability test.

6.5 **DOCUMENTATION**

Documentation of Screening Tests shall be in accordance with Para. 9.7.

7. **QUALIFICATION, QUALIFICATION MAINTENANCE AND LOT VALIDATION TESTING**

Requirements of this paragraph are applicable to the tests performed for component type qualification and qualification maintenance, qualification and qualification maintenance of a component within a capability approved domain and also for Lot Validation Testing.

7.1 **COMPONENT TYPE QUALIFICATION TESTING**

7.1.1 **General**

Qualification testing shall be in accordance with the requirements given in Chart F4. The tests of Chart F4 shall be performed on the specified sample, chosen at random from components which have successfully passed the tests in Chart F3 (Screening Tests). This sample constitutes the qualification test lot.

The qualification test lot is divided into subgroups of tests and all components assigned to a subgroup shall be subjected to all of the tests in that subgroup, in the sequence shown. The applicable test requirements are detailed in the paragraphs referenced in Chart F4.

The conditions governing component type qualification testing are given in ESCC Basic Specification No. 20100.

7.1.2 Distribution within the Qualification Test Lot

The qualification test lot shall be comprised in accordance with the following provisions, depending on whether it is required to obtain qualification for a single component type or for a family of component types.

7.1.2.1 *Single Component Type*

When it is proposed to submit a single component for qualification testing, the sample quantity shall be as specified in Chart F4, Note 1. However, when such a single component type is to be qualified in more than 1 type of package, each package variation must be equally represented in, the environmental/mechanical subgroup (Subgroup 1), the endurance subgroup (Subgroup 2) and the assembly/capability subgroup (Subgroup 3). For this purpose, the applicable sample distribution shall be the same as for the qualification of a family of component types as specified in Chart F4, Note 2 or Note 3.

7.1.2.2 *Family of Component Types*

A family of component types is a series of components produced by the same manufacturing techniques, up to and including final encapsulation, using the same types of machines and apparatus. Such components will be designed for the same supply, bias and signal voltages and for an input/output compatibility with each other under an established set of loading rules. They shall be produced using the same technology (e.g. the same diffusion schedules, method of metallisation, etc.) and identical design rules.

Qualification may be granted to a family of components subject to the successful outcome of the qualification testing of certain specified component types to represent the family.

Structurally similar components from such a family may be grouped together for the purpose of selecting samples for qualification testing. The component types selected must adequately represent all of the various mechanical, structural and electrical elements encountered within the family.

The component types chosen must be those that employ the extremes of design rules and tolerances and contain the maximum of internal sub-circuitry complexity, i.e. usually those that give the greatest risk of rejection.

When qualification is required for component types in more than one type of package, each package must be adequately represented in the environmental/mechanical subgroup (Subgroup 1) and in the assembly/capability subgroup (Subgroup 3).

The component types may be specified by, but in any case shall be agreed with, the ESCC Executive, prior to the commencement of qualification testing and the justification for the selection shall be declared in the qualification test report.

The number of component types selected as representative of the family will therefore determine the total number of components comprising the qualification test lot. Depending on the number of types selected, the sample sizes shall be as specified Chart F4, Note 2 or Note 3.

In the case of four or more component types selected, different pass/fail criteria from those shown in Chart F4 may be applicable. When appropriate, these shall be agreed with the ESCC Executive prior to the commencement of qualification testing.

7.2 QUALIFICATION WITHIN A CAPABILITY APPROVED DOMAIN

The qualification of a component within a capability approved domain shall be in accordance with ESCC Basic Specification No. 24300.

7.3 QUALIFICATION MAINTENANCE (PERIODIC TESTING)

Component type qualification is maintained through periodic testing and the test requirements of Para. 7.1 shall apply. For each subgroup the period between successive subgroup testing shall be as given in Chart F4. The conditions governing qualification maintenance are given in ESCC Basic Specification No. 20100.

Qualification of a component within a capability approved domain is maintained by periodic testing as specified in ESCC Basic Specification No. 24300.

7.4 LOT VALIDATION TESTING

7.4.1 General

For qualified components, Lot Validation Testing as defined in compliance with Chart F4, Subgroup 2, shall only be performed on the procured lot if required in the Purchase Order.

If unqualified components are procured using this specification then the Orderer shall define in the Purchase Order the required subgroups from Chart F4 to be used for Lot Validation Testing.

7.4.2 Distribution within the Sample for Lot Validation Testing

Where the Detail Specification covers a range, or series, of components that are considered similar, then it is only necessary to perform Lot Validation Testing on representative types if a number of different types are procured together. The sample for Lot Validation Testing should be comprised of component types so selected that they adequately represent all of the various mechanical, structural and electrical peculiarities of the components procured from the range or series.

The distribution of component types will vary from procurement to procurement and shall be as required in the Purchase Order.

7.5 FAILURE CRITERIA

The following criteria shall apply to ^{qualification, qualification maintenance} ~~Qualification and Periodic Tests~~ and ~~Lot~~ Lot Validation Testing.

7.5.1 Environmental and Mechanical Test Failures

The following shall be counted as component failures:-

Components which fail during tests for which the pass/fail criteria are inherent in the test method, e.g. Seal, Terminal Strength, etc.

7.5.2 Electrical Failures

The following shall be counted as component failures:

Components which fail one or more of the applicable limits at each of the relevant data points specified for environmental, mechanical and endurance testing in Intermediate and End-point Electrical Measurements in the Detail Specification.

7.5.3 Other Failures

A component shall be counted as a failure in any of the following cases:



- Visual Inspection failure
- Mechanical failure
- Handling failure
- Lost component

7.6 **FAILED COMPONENTS**

A component shall be considered as failed if it exhibits one or more of the failure modes detailed in Para. 7.5.

When requested by the ESCC Executive (for qualification, qualification maintenance or procurement of qualified components) or the Orderer (for procurement of qualified or unqualified components), failure analysis of failed components shall be performed by the Manufacturer and the results provided.

Failed components shall be retained at the Manufacturer's plant until the final disposition has been agreed and certified.

7.7 **LOT FAILURE**

For qualification and qualification maintenance, the lot shall be considered as failed if one component in any subgroup of Chart F4 is a failed component based on the criteria given in Para. 7.5.

For procurement, the lot shall be considered as failed if one component in any test specified for Lot Validation Testing is a failed component based on the criteria given in Para. 7.5.

In the case of lot failure, the Manufacturer shall act in accordance with Para. 4.3.1.

7.8 **QUALIFICATION, QUALIFICATION MAINTENANCE AND LOT VALIDATION TESTING SAMPLES**

All tests of Chart F4 are considered to be destructive and therefore components so tested shall not form part of the delivery lot.

7.9 **DOCUMENTATION**

qualification, qualification maintenance and Lot Validation Testing
Documentation of ~~Qualification and Periodic Tests~~ shall be in accordance with Para. 9.8.

8. **TEST METHODS AND PROCEDURES**

If a Manufacturer elects to eliminate or modify a test method or procedure, the Manufacturer is still responsible for delivering components that meet all of the performance, quality and reliability requirements defined in this specification and the Detail Specification.

For a qualified component, documentation supporting the change shall be approved by the ESCC Executive and retained by the Manufacturer. It shall be copied, when requested, to the ESCC Executive. The change shall be specified in an appendix to the Detail Specification and in the PID.

For an unqualified component the change shall be approved by the Orderer. The change may be specified in an appendix to the Detail Specification at the request of the Manufacturer or Orderer, subject to the approval of the ESCC Executive.

8.1 **INTERNAL VISUAL INSPECTION**

ESCC Basic Specification No. 20400.

8.2 BOND STRENGTH AND DIE SHEAR

8.2.1 Bond Strength

MIL-STD-883 Test Method 2011

- Test condition 'C' or 'D' for thermo-compression, ultrasonic or wedge bonding.
- Test condition 'F' for flip-chip bonding.
- Test condition 'G' or 'H' for beam lead bonding.

Test samples: For Special In-Process Controls the required test samples shall be selected at random from the lot of components accepted after Internal Visual Inspection.

For Qualification and Periodic Tests the required test samples shall be selected from the components in Subgroup 3 of Chart F4.

Quantity of internal bond wires 8 or less; Test samples = 3, Test all bonds

Quantity of internal bond wires 9 to 24; Test samples = 2, Test all bonds

Quantity of internal bond wires 25 or more; Test samples = 2, Test 50% of bonds

If agreed by the ESCC Executive (for qualification or qualification maintenance) or the Orderer (for procurement) the test samples for Special In-Process Controls may have only passed the low magnification phase of the Internal Visual Inspection.

Individual separation forces and categories shall be recorded. A single failure shall be cause for lot failure.

8.2.2 Die Shear

MIL-STD-883 Test Method 2019

The same test samples submitted to Bond Strength shall be used. Individual separation forces and categories shall be recorded. A single failure shall be cause for lot failure.

8.3 SCANNING ELECTRON MICROSCOPE INSPECTION

ESCC Basic Specification No. 21400.

8.4 TOTAL DOSE RADIATION TESTING

ESCC Basic Specification No. 22900 to the total dose level specified in the Detail Specification or as required in the Purchase Order.

8.5 HIGH TEMPERATURE STABILISATION BAKE

MIL-STD-883, Test Method 1008, Duration: 24 hours at maximum storage temperature rating specified in the Detail Specification.

8.6 TEMPERATURE CYCLING

MIL-STD-883, Test Method 1010. Test Condition: C.

8.7 PARTICLE IMPACT NOISE DETECTION (PIND)

Only applicable to devices with cavities.



MIL-STD-883, Test Method 2020, Test Condition A.

8.8 SEAL

8.8.1 Seal, Fine Leak

MIL-STD-883, Test Method 1014, Condition A or B.

8.8.2 Seal, Gross Leak

MIL-STD-883, Test Method 1014, Condition C.

8.9 ELECTRICAL MEASUREMENTS

8.9.1 Parameter Drift Values

At each of the relevant data points during Screening Tests, Parameter Drift Values shall be measured as specified in the Detail Specification. All values obtained shall be recorded against serial numbers and the parameter drift calculated.

8.9.2 High and Low Temperatures Electrical Measurements

High and Low Temperatures Electrical Measurements shall be performed as specified in the Detail Specification. All values obtained shall be recorded against serial numbers.

8.9.3 Room Temperature Electrical Measurements

Room Temperature Electrical Measurements shall be performed as specified in the Detail Specification. All values obtained shall be recorded against serial numbers.

8.9.4 Intermediate and End-Point Electrical Measurements

At each of the relevant data points during Qualification and Periodic Tests Intermediate and End-point Electrical Measurements shall be performed as specified in the Detail Specification. All values obtained shall be recorded against serial numbers and the parameter drift calculated, if specified.

8.10 EXTERNAL VISUAL INSPECTION AND DIMENSION CHECK

External Visual Inspection shall be performed in accordance with ESCC Basic Specification No. 20500.

Dimension check (during Special In-Process Controls only) shall be performed in accordance with ESCC Basic Specification No. 20500 and the Detail Specification on a sample of 3 components. If a failure occurs the complete lot shall be checked.

8.11 MECHANICAL SHOCK

MIL-STD-883, Test Method 2002, Test Condition: B.

8.12 VIBRATION

MIL-STD-883, Test Method 2007, Test Condition: A.

8.13 CONSTANT ACCELERATION

MIL-STD-883, Test Method 2001, Test Condition: E (resultant centrifugal acceleration to be in the Y1 axis only). For components which have a package weight of 5 grammes or more, or whose inner seal or



cavity perimeter is more than 5 cm, Condition D shall be used.

8.14 THERMAL SHOCK
MIL-STD-883, Test Method 1011, Test Condition C.

8.15 MOISTURE RESISTANCE
MIL-STD-883, Test Method 1004.

8.16 SOLDERABILITY
For procurement lots: 5 samples.

MIL-STD-883, Test Method 2003, to be performed on all terminals.

Solderability testing may be performed on empty packages or electrical rejects. The test samples used must be of the same package type and must have been manufactured using the same process, at the same time and have been subjected to the same screening as the packages of the delivery lot with which they are associated.

For components with gold plated lead finish activated fluxes (RMA and RA) may be used but shall be immediately cleaned off after dipping using an acceptable solvent.

Solderability testing is classed as destructive and therefore components so tested shall not form part of the delivery lot.

8.17 PERMANENCE OF MARKING
ESCC Basic Specification No. 24800.

8.18 TERMINAL STRENGTH
MIL-STD-883, Test Method 2004, Test Condition D for chip carrier packages or Test Condition B2 for all other packages. For Condition B2, 3 leads (excluding corner leads) or 10% of the leads (whichever is greater) shall be randomly selected on each component.

8.19 OPERATING LIFE
MIL-STD-883, Test Method 1005.

– Duration: 2000 hours.

– Conditions: As specified in Operating Life in the Detail Specification.

– Data Points

As specified in Intermediate and End-point Electrical Measurements in the Detail Specification at 0 hours, 1000 ± 48 hours and 2000 ± 48 hours. If drift values are specified, the drift shall always be related to the 0-hour measurement.

8.20 HIGH TEMPERATURE REVERSE BIAS BURN-IN
– MIL-STD-883, Test Method 1015, Test Condition A.

- Duration and Test Conditions
As specified, where applicable, in High Temperature Reverse Bias Burn-in in the Detail Specification.
- Data Points
As specified in the Parameter Drift Values in the Detail Specification at 0 hours and T (+24 -0) hours (where T is the specified duration).

8.21

POWER BURN-IN

MIL-STD-883, Test Method 1015 Test Condition B, D or E.

- Duration
Unless otherwise specified in the Detail Specification, components shall be subjected to a total power burn-in period of 240 (+24 -0) hours.
- Test Conditions
As specified in Power Burn-in in the Detail Specification.
The alternative temperature and time combinations per MIL-STD-883 method 1015 are permissible provided that the maximum operating ratings for a component are not exceeded.
- Data Points
As specified in Parameter Drift Values in the Detail Specification at T (+24 -0) hours (where T is the specified duration).
If High Temperature Reverse Bias Burn-in is not being performed, the 0 hours (initial) measurement is also required.

9. DATA DOCUMENTATION**9.1 GENERAL**

For the qualification, qualification maintenance and procurement for each lot a data documentation package shall exist in a printed or electronic form.

This package shall be compiled from:

- (a) Cover sheet (or sheets).
- (b) List of equipment (testing and measuring).
- (c) List of test references.
- (d) Special In-Process Controls data (Chart F2).
- (e) Wafer Lot Acceptance data (Chart F2).
- (f) Screening Tests data (Chart F3).
- (g) Qualification and Periodic Tests data (Chart F4), including Lot Validation Testing data (when applicable) (Chart F4)
- ~~(h) Lot Validation Testing data (when applicable).~~
- (h) Failed components list and failure analysis report (when applicable).
- (i) Certificate of Conformity.

Items (a) to (i) inclusive shall be grouped, preferably as subpackages and, for identification purposes, each page shall include the following information:

- ESCC Component Number.
- Manufacturer's name.
- Lot identification.
- Date of establishment of the document.
- Page number.

Whenever possible, documentation should preferably be supplied in electronic format suitable for reading using a compatible PC. The format supplied shall be legible, durable and indexed. The preferred storage media are 3 1/2 inch diskettes or CD-ROMs and the preferred file formats are ASCII or PDF.

9.1.1 Qualification and Qualification Maintenance

In the case of qualification or qualification maintenance, the items listed in Para. 9.1(a) to ~~(j) less item (h)~~ are required.

9.1.2 Component Procurement and Delivery

For all deliveries of components procured to this specification, the following documentation shall be supplied:

- (a) Cover sheet (if all of the information is not included on the Certificate of Conformity).
- (b) Certificate of Conformity (including range of delivered serial numbers).

9.1.3 Additional Documentation

The Manufacturer shall deliver additional documentation containing data and reports to the Orderer, if required in the Purchase Order.

9.1.4 Data Retention/Data Access

If not delivered, all data shall be retained by the Manufacturer for a minimum of 5 years during which time it shall be available for review, if requested, by the Orderer or the ESCC Executive (for qualified components).

9.2 COVER SHEET(S)

The cover sheet(s) of the data documentation package shall include as a minimum:

- (a) Reference to the Detail Specification, including issue and date.
- (b) Reference to the applicable ESCC Generic Specification, including issue and date.
- (c) ESCC Component Number and the Manufacturers part type number.
- (d) Lot identification.
- (e) Range of delivered serial numbers.
- (f) Number of the Purchase Order.
- (g) Radiation testing level (if applicable).
- (h) Information relative to any additions to this specification and/or the Detail Specification.
- (i) Manufacturer's name and address.
- (j) Location of the manufacturing plant (specify place of diffusion, assembly and test).
- (k) Signature on behalf of Manufacturer.
- (l) Total number of pages of the data package.

9.3 LIST OF EQUIPMENT USED

A list of equipment used for tests and measurements shall be prepared, if not in accordance with the data given in the PID. Where applicable, this list shall contain inventory number, Manufacturer's type number,

serial number, etc. This list shall indicate for which tests such equipment was used.

9.4 LIST OF TEST REFERENCES

This list shall include all Manufacturer's references or codes which are necessary to correlate the test data provided with the applicable tests specified in the tables of the Detail Specification.

9.5 SPECIAL IN-PROCESS CONTROLS DATA (CHART F2)

A test result summary shall be compiled, showing the total number of components submitted to, and the total number rejected after each of the tests. For the ~~Bond~~ strength and ~~Die~~ shear tests, the separation forces and categories shall be recorded.

Bond Strength Die Shear

9.6 WAFER LOT ACCEPTANCE DATA (CHART F2)

Data of ~~SEM~~ Inspection shall be prepared in accordance with the requirements of ESCC Basic Specification No. 21400.

Radiation test report shall be prepared in accordance with the requirements of ESCC Basic Specification No. 22900 (if specified).

9.7 SCREENING TESTS DATA (CHART F3)

A test result summary shall be compiled showing the total number of components submitted to and the total number rejected after each of the tests. For each test requiring electrical measurements the results shall be recorded against component serial number. Component drift calculations shall be recorded for each specified test against component serial number.

9.8 QUALIFICATION AND PERIODIC TESTS DATA (CHART F4)

9.8.1 Qualification Tests

A test result summary shall be compiled showing the components submitted to and the number rejected after each test in each subgroup. Component serial numbers for each subgroup shall be identified. For each test requiring electrical measurements the results shall be recorded against component serial number. Where a drift value is specified during a test the drift calculation shall be recorded against component serial number.

9.8.2 Periodic Tests for Qualification Maintenance

A test result summary shall be compiled showing the components submitted to and the number rejected after each test in each subgroup. Component serial numbers for each subgroup shall be identified. For each test requiring electrical measurements the results shall be recorded against component serial number. Where a drift value is specified during a test the drift calculation shall be recorded against component serial number.

In addition to the full test data a report shall be compiled for each subgroup of Chart F4 to act as the most recent ~~Periodic Testing~~ summary. These reports shall include a list of all tests performed in each subgroup, the ESCC Component Numbers and quantities of components tested, a statement confirming all the results were satisfactory, the date the tests were performed and a reference to the full test data.

9.8.3 Lot Validation Testing

A test result summary shall be compiled showing the components submitted to and the number rejected after each test in each subgroup (as applicable). Component serial numbers for each subgroup shall be identified. For each test requiring electrical measurements the results shall be recorded against



component serial number. Where a drift value is specified during a test the drift calculation shall be recorded against component serial number.

9.9 **FAILED COMPONENTS LIST AND FAILURE ANALYSIS REPORT**

The failed components list and failure analysis report shall provide full details of:

- (a) The reference and description of the test or measurement performed as defined in this specification and/or the Detail Specification during Special In-Process Controls, Wafer Lot Acceptance, Screening Tests and Qualification and Periodic Tests.
- (b) The serial number (if applicable) of the failed component.
- (c) The failed parameter and the failure mode of the component.
- (d) Detailed failure analysis ~~if~~ requested by the ESCC Executive or Orderer).

9.10 **CERTIFICATE OF CONFORMITY**

A Certificate of Conformity shall be established as defined in ESCC Basic Specification No. 20100 or ESCC Basic Specification No. 24300.

10. **DELIVERY**

For procurement, for each order, the items forming the delivery are:

- (a) The delivery lot.
- (b) The components used for Lot Validation Testing (when applicable), but not forming part of the delivery lot.
- (c) The relevant documentation in accordance with the requirements of Section 9.

In the case of a component for which a valid qualification is in force, all data of all components submitted to Lot Validation Testing shall also be copied, when requested, to the ESCC Executive.

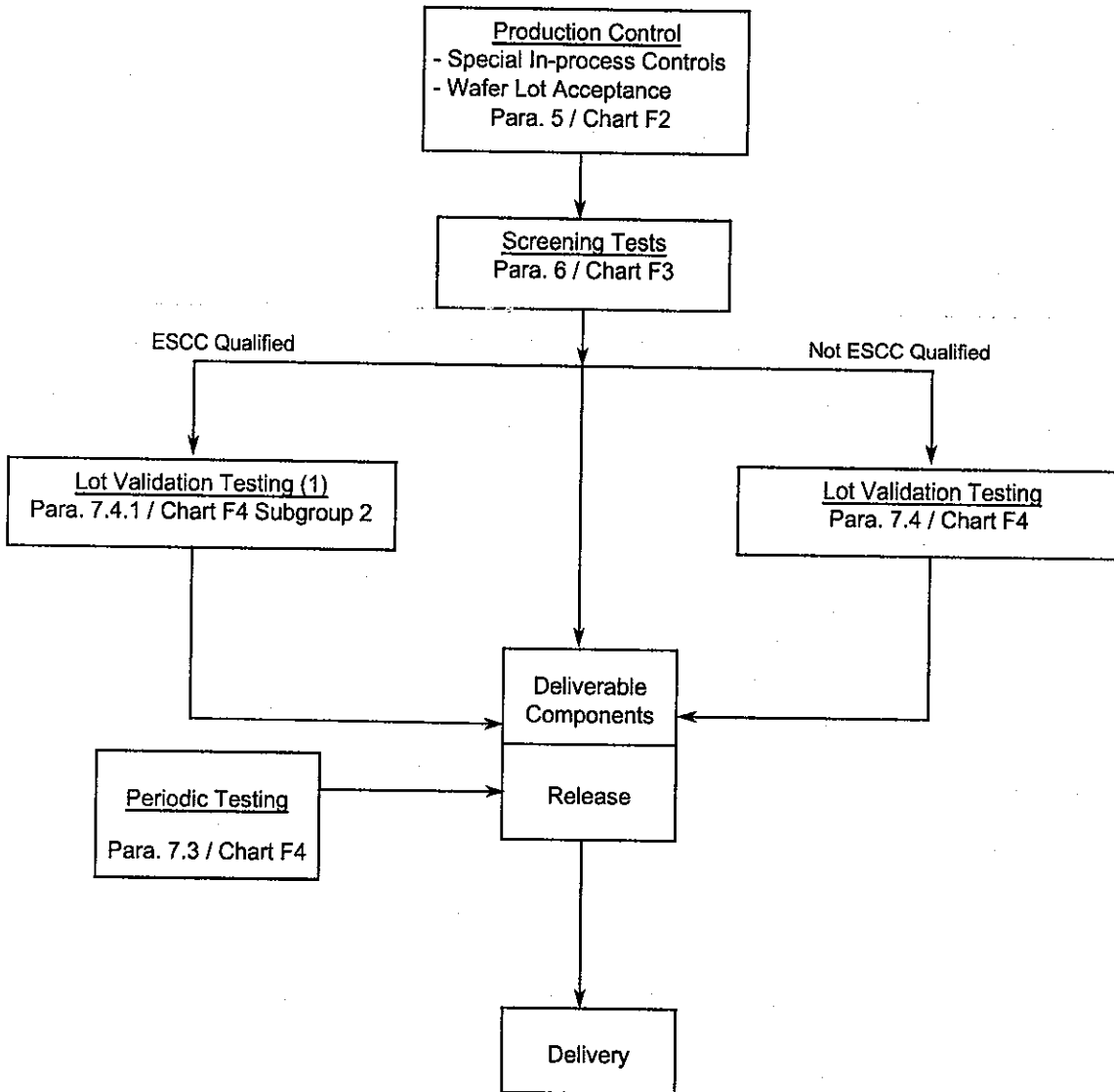
For qualification or qualification maintenance, the disposition of the test lot and its related documentation shall be as specified in ESCC Basic Specification Nos. 20100 or 24300 and the relevant paragraphs of Section 9 of this specification.

11. **PACKAGING AND DISPATCH**

The packaging and dispatch of components to this specification shall be in accordance with the requirements of ESCC Basic Specification No. 20600.

12. **CHARTS**

12.1 **CHART F1 - GENERAL FLOW FOR PROCUREMENT**



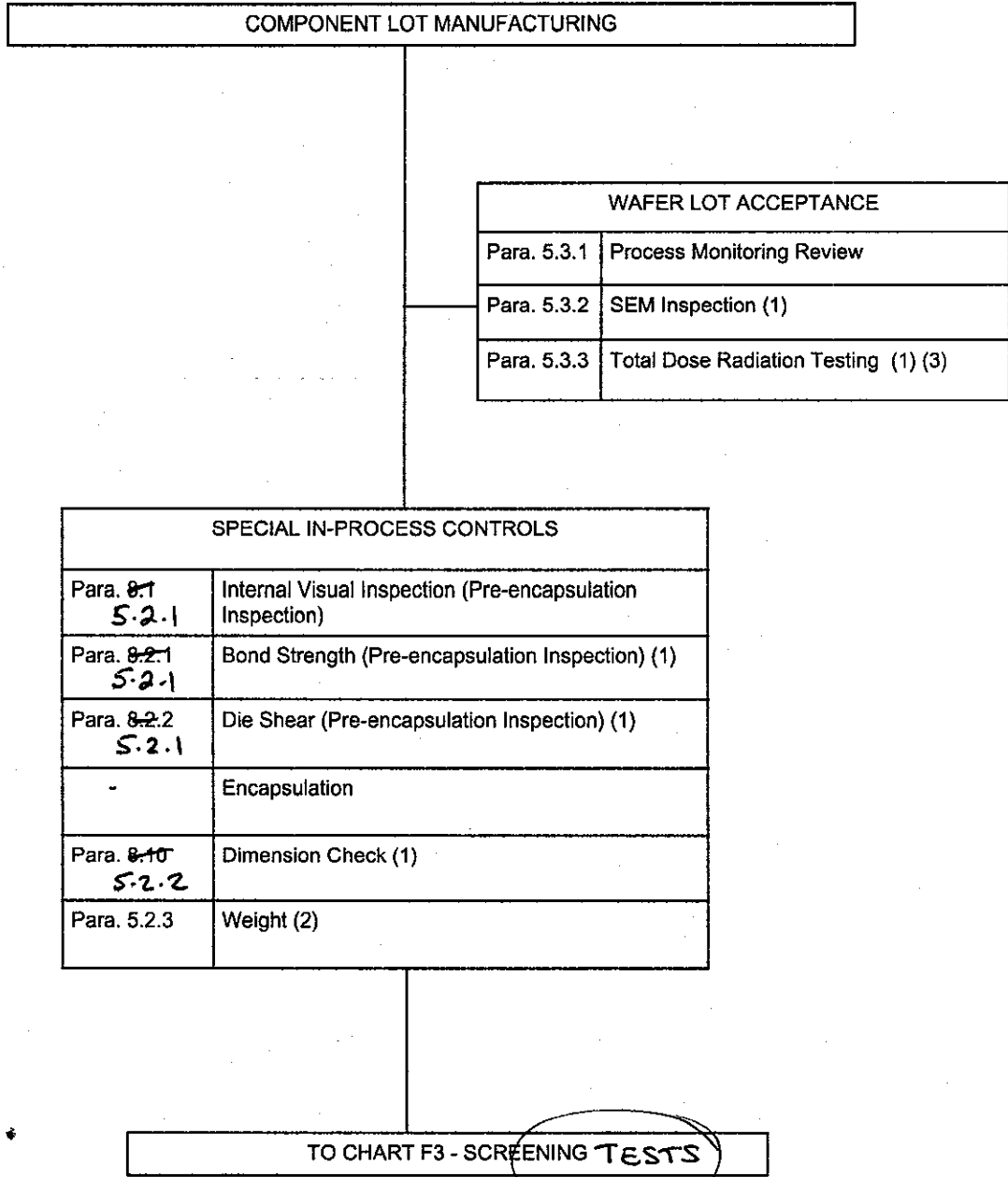
NOTES:

1. Lot Validation Testing is optional for qualified components and shall only be performed if required in the Purchase Order.



12.2

CHART F2 - PRODUCTION CONTROL



NOTES:

1. Performed on a sample basis.
2. Guaranteed but not tested.
3. If specified in the Detail Specification and required in the Purchase Order.

12.3

CHART F3 - SCREENING TESTS

COMPONENTS FROM PRODUCTION CONTROL		(1)
Para. 8.5	High Temperature Stabilisation Bake	
Para. 8.6	Temperature Cycling	
Para. 8.7	Particle Impact Noise Detection (PIND)	
Para. 8.9.1	Parameter Drift Values (Initial Measurements)	
Para. 8.20	High Temperature Reverse Bias Burn-in	
Para. 8.9.1	Parameter Drift Values (Final Measurements for HTRB; Initial Measurements for Power Burn-in)	(4) (2)
Para. 8.21	Power Burn-in	
Para. 8.9.1	Parameter Drift Values (Final Measurements)	(4) (2)
Para. 8.9.2	High and Low Temperatures Electrical Measurements	(4) (2)
Para. 8.9.3	Room Temperature Electrical Measurements	(2) (4) (4)
Para. 6.4.1	Check for Lot Failure	(5) (5)
Para. 8.8.1 and Para. 8.8.2	Seal (Fine and Gross Leak)	
Para. 8.10	External Visual Inspection	
Para. 8.16	Solderability	(2) (4) (2) (5)
TO CHART F4 WHEN APPLICABLE		

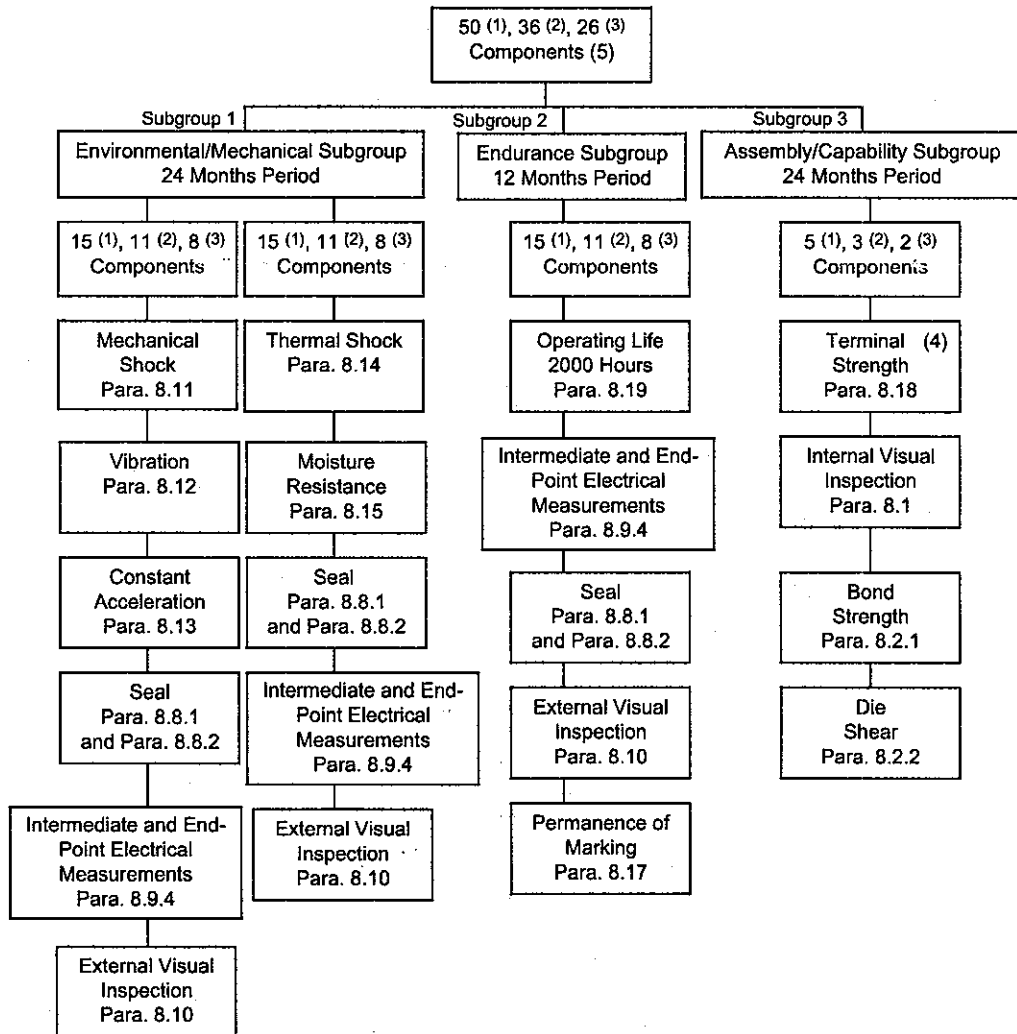
NOTES:

1. All components shall be serialised prior to Screening Tests.
- 4 2. Measurements of Parameter Drift Values need not be repeated in Room Temperature Electrical Measurements.
- 6 3. Performed on a sample basis.
- 2A 4. The lot failure criteria of Para. 6.4 apply to this test.
- 5 5. Check for Lot Failure shall take into account all electrical parameter failures that may occur during

-	Hot Solder Dip (if applicable)	(3)
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Screening Tests in accordance with Para. 8.9.1, 8.9.2, 8.9.3 subsequent to HTRB Burn-in.

12.4 CHART F4 - QUALIFICATION AND PERIODIC TESTS



NOTES:

1. Single type (see Para. 7.1.2.1)
2. Per type for two types selected (see Para. 7.1.2.2)
3. Per type for three or more types selected (see Para. 7.1.2.2)
4. May be done at the beginning or the end of the subgroup, depending on package configuration.
5. No failures are permitted.

Chart F3. ← 3. For components with hot solder dip final lead finish the hot solder dip processing shall be performed at any time prior to Room Temperature Electrical Measurements during Screening Tests. The requirements for hot solder dip are specified in ESCC Basic Specification No. 23500.